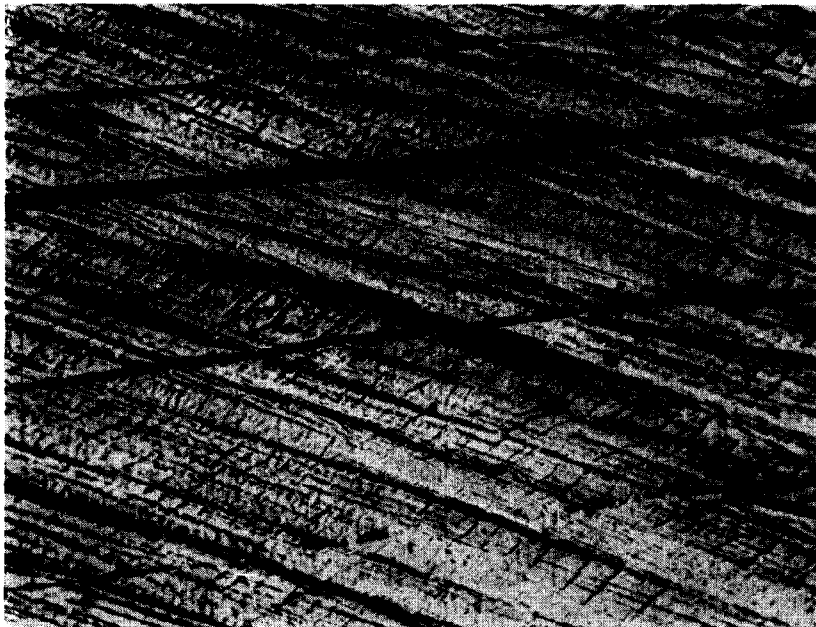


FIG. 2. (a) Slip through twinned $[111]$ crystal. Twin lamellae are the white traces; tensile axis horizontal, (110) surface, $\times 500$.



(b) Laminated structure of twinned and untwinned matrix. Traces of twin plane run diagonally down from left to right; tensile axis horizontal, (110) surface, $\times 250$.

parallel to $(\bar{1}\bar{1}\bar{1})$ and T_1 . From Fig. 1 it is evident that slip can take place on $T_4 [011]$, $T_3 [\bar{1}10]$ and on T_1 in $[011]$ and $[\bar{1}10]$ without violating strain compatibility. Furthermore $T_4 [011]$ can criss-slip onto $(\bar{1}\bar{1}\bar{1})$ and $T_3 [\bar{1}10]$ onto (111) . It was possible to determine from the angular deflection as the slip trace crossed the twin boundary which $\{111\}$ planes were continuous[†]. In every case it was found to be either $T_4 \cdot (\bar{1}\bar{1}\bar{1})$ or $T_3 \cdot (111)$.

Figure 2(a) clearly shows the continuity of the slip traces as slip proceeds across a twinned region. In highly twinned regions, short transverse traces become more predominant (Fig. 2(b)) and near the fracture these traces join up. Slipping off occurs by localized shear in a zone parallel to these traces.

Upon twinning the Schmid factor for the systems $T_4 [011]$ and $T_3 [\bar{1}10]$ becomes 0.455 compared to 0.272 for all active slip systems in the original orientation. Hence should a shear stress concentration build up at the twin plane, Livingston and Chalmers' analysis⁽⁵⁾ of computing resolved shear stresses on slip systems across a grain boundary shows that the most highly stressed systems in the original matrix are the $(\bar{1}\bar{1}\bar{1}) [011]$ and $(111) [\bar{1}10]$. These systems are precisely those which are favored from strain compatibility conditions.

From the symmetry of $(\bar{1}\bar{1}\bar{1}) [011] - T_4 [011]$ and $(111) [\bar{1}10] - T_3 [011]$ combinations with respect to the tensile axis, for a crystal which upon twinning still remains geometrically uniform, double shear is expected. A crystal displaying just this has been observed.⁽⁶⁾ For twinned crystals originally oriented for single slip, one of the above combinations has a larger resolved shear stress and hence planar shear would be expected. The shear fracture in twinned crystals observed by Blewitt *et al.*⁽⁷⁾ could be explained in this way.

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S. SAIMOTO[‡]

W. F. HOSFORD, Jr.[§]

W. A. BACKOFEN

*Metals Processing Laboratory
Massachusetts Institute of Technology
Cambridge, U.S.A.*

[†] This determination was facilitated by the fact that the lattice rotation in $[\bar{1}\bar{1}\bar{1}]$ crystals was small making the surface analysis simple. Furthermore, the measurements were made on the thick end of slightly tapered crystals where the Lüders front had terminated.

[‡] Now at: Division of Pure Physics, National Research Council, Ottawa, Canada.

[§] Now at: Chemical and Metallurgical Engineering Department University of Michigan, Ann Arbor, U.S.A.

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A note on the creep substructure of pure copper*

The purpose of this note is to report some observations made on the dislocation substructure present during steady state creep of 99.995% Cu. Creep samples were tested in a dry deoxidized hydrogen atmosphere under condition of constant stress on a creep unit equipped with a sliding furnace. The furnace assembly was such that following testing the entire furnace was lowered and the specimen cooled rapidly under load. The cooling rate above 100°C was approximately 300°C per min. Specimens were maintained in the hydrogen atmosphere during the entire cooling cycle. It was hoped that the rapid cool while under load would preserve the existing creep substructure.

Following testing, samples were chemically polished to a thickness of ~ 0.05 mm (initial thickness ~ 1.25 mm) using a solution of 50 ml HNO_3 , 25 ml H_3PO_4 and 25 ml glacial acetic acid. Thin foils were then prepared by electro polishing in a solution of 67 ml methyl alcohol and 33 ml HNO_3 maintained at -30°C . All transmission microscopy was performed with a Hitachi Hu 11 electron microscope operating at 100 kV.

All samples were fully recrystallized at 700°C prior to testing. This annealing treatment resulted in an average grain diameter of 0.22 mm. The as-annealed structure was free from substructure apart from a few randomly spaced dislocations.

A typical creep substructure for a sample strained 6.1% at 496°C and 2.07×10^8 dyn/cm² is shown in Fig. 1. The steady state creep rate for this sample was 3.6×10^{-7} sec⁻¹. The subgrain boundaries are generally well defined two-dimensional dislocation networks and do not resemble the tangled networks that characterize the low temperature deformation substructure of copper.⁽¹⁾ Rather the structure is more typical of a cold worked and recovered substructure, as might be expected from the high temperature creep conditions. The average subgrain diameter is 3.3 μ . Two examples